

CLEANING APPARATUS, PLATING APPARATUS USING THE SAME,  
AND CLEANING METHOD

ABSTRACT OF THE DISCLOSURE

To clean a substrate with reduced influence on resist patterns, wires, and the like on the surface of the substrate. A cleaning apparatus is provided. This cleaning apparatus includes an inlet for a target object, an outlet for the target object, a first conveyance path on which the target object input through the inlet is conveyed, a second conveyance path on which the target object is conveyed in a direction opposite to a direction of conveyance of the target object on the first conveyance path and that is connected with the first conveyance path and the outlet, a cleaning unit disposed on the first conveyance path and configured to clean the target object in a non-contacting manner, and a drying unit disposed on the first conveyance path and configured to dry the target object in a non-contacting manner. The first conveyance path and the second conveyance path are vertically arranged side by side. The second conveyance path is positioned above the first conveyance path and connected with the outlet at an end point. The second conveyance path functions as a stocker configured to temporarily store the target object.

Selected Drawing: FIG. 2